

canceled claims 1-21 has not been presented.

AMENDMENTS TO THE CLAIMS

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22. (currently amended) A method for mounting multilayered ceramic capacitors on a circuit board having a front surface and a back surface, wherein each capacitor includes a body having dielectric layers formed of a dielectric ceramic material and internal electrode layers and a pair of external terminal electrodes formed on two sides of the body, the dielectric layers and the internal electrode layers being stacked alternately in the body and the internal electrode layers being connected in parallel to the external terminal electrodes in an alternate manner, the method comprising the steps of:

forming lands at substantially plane-symmetrical positions on the front and the back surfaces, wherein every two lands disposed at their substantially plane-symmetrical positions are connected each other; and

mounting the capacitors on the lands of the front and the back surfaces and electrically coupling the external terminal electrodes of the capacitors to the lands on the front and the back surfaces,

wherein voltages applied to the capacitors have frequencies varying in an audible frequency band.

23. (currently amended) The method of claim 22, wherein said two lands are electrically coupled to each other by a through hole formed therein.

24. (previously added) The method of claim 22, wherein the capacitors are substantially identical each other.

25. (previously added) The method of claim 22, wherein the capacitors are connected in parallel.

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26. (previously added) The method of claim 22, wherein voltages applied to the capacitors are varied.

27. (canceled)

28. (currently amended) A method for mounting multilayered ceramic capacitors on a circuit board having a front surface and a back surface, wherein each capacitor includes a body having dielectric layers formed of a dielectric ceramic material and internal electrode layers and a pair of external terminal electrodes formed on two sides of the body, the dielectric layers and the internal electrode layers being stacked alternately in the body and the internal electrode layers being connected in parallel to the external terminal electrodes in an alternate manner, the method comprising the step of:

mounting the capacitors on substantially plane-symmetrical positions of the front and the back surfaces, respectively, wherein the capacitors are substantially identical each other and substantially identical voltages are applied to the capacitors,

wherein voltages applied to the capacitors have frequencies varying in an audible frequency band.

29. (previously added) The method of claim 28, wherein said mounting step includes the steps of:

forming lands at substantially plane-symmetrical positions on the front and the back surfaces, wherein every two lands disposed at their substantially plane-symmetrical positions are connected each other; and

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mounting the capacitors on the lands of the front and the back surfaces such that the external terminal electrodes of the capacitors are electrically coupled to the lands on the front and the back surfaces.

30. (currently amended) The method of claim 29, wherein said two lands are electrically coupled to each other by a through hole formed therein.

31. (canceled)

32. (previously added) The method of claim 28, wherein the capacitors are connected in parallel.

33. (previously added) The method of claim 28, wherein voltages applied to the capacitors are varied.

34. (canceled)

35. (currently amended) A method for mounting multilayered ceramic capacitors on a circuit board having a front and a back surfaces, the capacitors being used in an electronic circuit as components thereof and voltages applied to the capacitors being varied, wherein each capacitor includes a body having dielectric layers formed of a dielectric ceramic material and internal electrode layers and a pair of external terminal electrodes formed on two sides of the body, the dielectric layers and the internal electrode layers being stacked alternately in the body and the internal electrode layers being connected in parallel to the external terminal electrodes in an alternate manner, the method comprising the steps of:

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B1 forming lands at substantially plane-symmetrical positions on the front and the back surfaces, wherein every two lands disposed at their substantially plane-symmetrical positions are connected each other; and

mounting the capacitors on the lands of the front and the back surfaces such that the capacitors are disposed at substantially plane-symmetrical positions and the external terminal electrodes of the capacitors are electrically coupled to the lands on the front and the back surfaces, wherein the capacitors are substantially identical each other and substantially identical voltages are applied to the capacitors,

wherein voltages applied to the capacitors have frequencies varying in an audible frequency band.

36. (previously added) The method of claim 35, wherein said two lands are electrically coupled to each other by a through hole formed therein.

37. (canceled)

38. (previously added) The method of claim 35, wherein the capacitors are connected in parallel.

39. (previously added) The method of claim 35, wherein voltages applied to the capacitors are varied.

40. (canceled)